

#### Features

- High luminous intensity output
- Oval Shape
- Well defined spatial radiation
- Wide viewing angle  $(2 \theta_{1/2}) : 110^{\circ} / 40^{\circ}$
- UV resistant epoxy
- The product itself will remain within RoHS compliant version

### 5484BN/R3DC-AEFC/XR/MS



#### Descriptions

- This precision optical performance oval LED is specifically designed for passenger information signs
- This lamp has matched radiation patterns with yellow, blue or green mixing color applications

#### Applications

- Color graphic signs
- Message boards
- Variable message signs (VMS)
- Commercial outdoor advertising

#### **Device Selection Guide**

LED Part No.	Chip Material	<b>Emitted Color</b>	Lens Color	Stopper
5484BN/R3DC-AEFC/R/MS				No
5484BN/R3DC-AEFC/PR/MS	AlGaInP	Brilliant Red	Red Diffused	Yes

Everlight Electronics Co., Ltd. Device Number : DT1-548-037 http\\:www.everlight.com Prepared date: 03-10-2008 Rev 1 Page: 1 of 10 Prepared by: Grace Shen

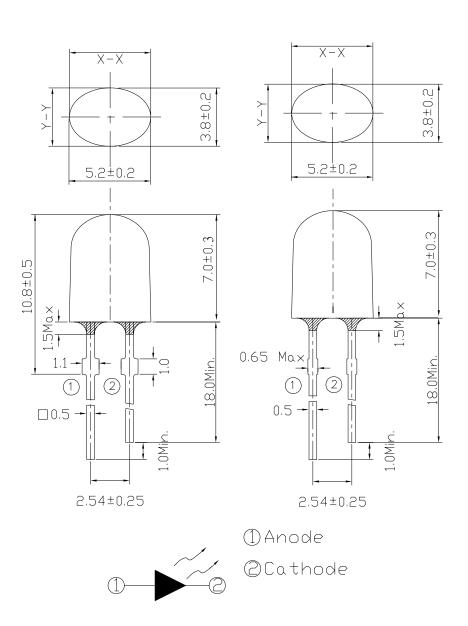


## 5484BN/R3DC-AEFC/XR/MS

#### **Package Dimensions**

#### **Stopper Type**

#### No Stopper Type



#### Notes:

- Other dimensions are in millimeters, tolerance is 0.25mm except being specified.
- Protruded resin under flange is 1.5mm Max LED.

Everlight Electronics Co., Ltd. Device Number : DT1-548-037 http\\:www.everlight.com Prepared date: 03-10-2008 Rev 1Page: 2 of 10Prepared by: Grace Shen

# 5484BN/R3DC-AEFC/XR/MS

Parameter	Symbol	Absolute Maximum Rating	Unit
Forward Current	$I_{\rm F}$	50	mA
Pulse Forward Current (Duty1/10@ 1KHz)	$I_{FP}$	160	mA
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +100	°C
Soldering Temperature	$T_{sol}$	260	°C
Power Dissipation	P <sub>d</sub>	120	mW
Reverse Voltage	VR	5	V
Electrostatic Discharge	ESD	2К	V

Absolute Maximum Rating (T<sub>a</sub>=25°C)

Notes: Soldering time  $\leq$  5 seconds.

### Electro-Optical Characteristics (T<sub>a</sub>=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	$I_V$	360		720	mcd	
Viewing Angle	$2 heta$ $_{ m 1/2}$		X:110Y:40		deg	
Peak Wavelength	$\lambda_{p}$		635			
Dominant Wavelength	$\lambda_d$	620		632	nm	I <sub>F</sub> =20mA
Spectrum Half width	Δλ		20			
Forward Voltage	$V_{\rm F}$	2.0		2.6	V	
Reverse Current	I <sub>R</sub>			10	$\mu A$	V <sub>R</sub> =5V

## Rank Combination (I<sub>F</sub>=20mA)

Rank	E1	E2	F1	F2
Luminous Intensity	360~430	430~510	510~610	610~720

\*Measurement Uncertainty of Luminous Intensity: ±10%

Rank	1	2
Dominant Wavelength	620~626	626~632

\*Measurement Uncertainty of Dominant Wavelength ±1.0nm

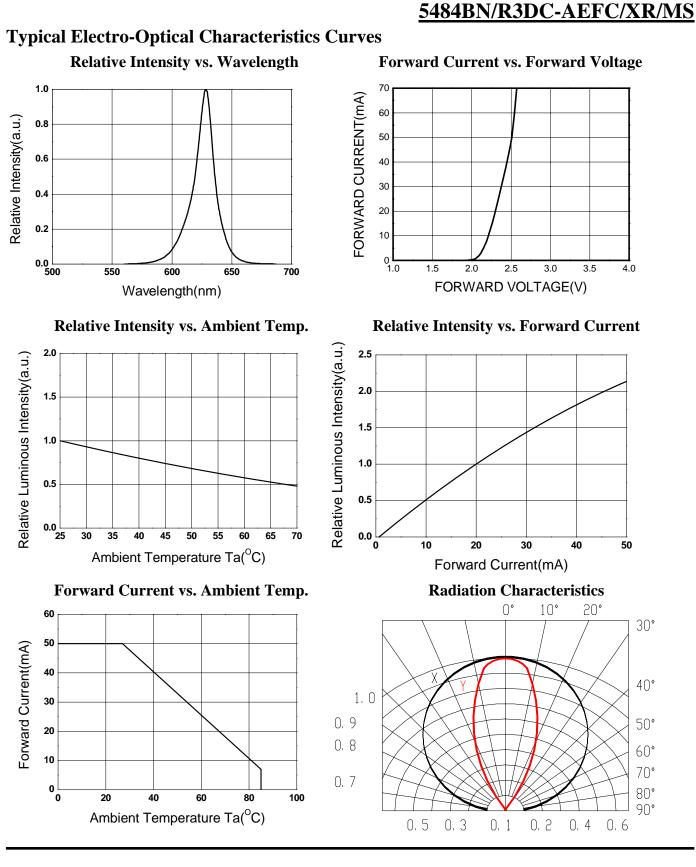
Everlight Electronics Co., Ltd. Device Number : DT1-548-037 http\\:www.everlight.com Prepared date: 03-10-2008 Rev 1Page: 3 of 10Prepared by: Grace Shen

Unit:mcd

Unit:nm

EVERLIGHT

## **Technical Data Sheet**

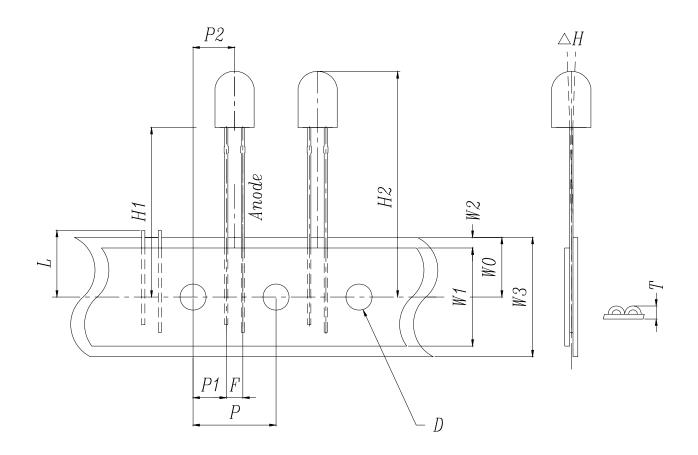


Everlight Electronics Co., Ltd. Device Number : DT1-548-037 http\\:www.everlight.com Prepared date: 03-10-2008 Rev 1Page: 4 of 10Prepared by: Grace Shen



# 5484BN/R3DC-AEFC/XR/MS

#### **Taping Dimensions**



Everlight Electronics Co., Ltd. Device Number : DT1-548-037 http\\:www.everlight.com Prepared date: 03-10-2008 Rev 1Page: 5 of 10Prepared by: Grace Shen



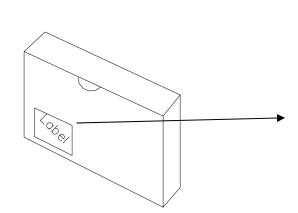
# 5484BN/R3DC-AEFC/XR/MS

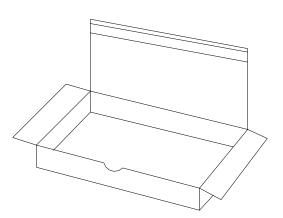
Taping Sizes					
		Specifications			
Symbol Items	Symbol	Avg.		Tolerance	
		mm	Inch	(mm)	
Tape Feed Hole Diameter	D	4.00	0.157	±0.2	
Component Lead Pitch	F	2.54	0.100	±0.3	
Front-to-Read Deflection	∆H	2.0	0.078	Max	
Feed Hole to Button of Component	H1	18.5	0.729	±1.0	
Feed Hole to Overall Component Height	H2	25.5	1.003	±1.0	
Lead Length after Component Removal	L	11.00	0.433	Max	
Feed Hole Pitch	Р	12.70	0.500	±0.3	
Lead Location	P1	5.10	0.200	±0.7	
Center of Component Location	P2	6.35	0.250	±1.2	
Overall Taped Package Thickness	Т	1.42	0.056	Max	
Feed Hole Location	W0	9.00	0.354	±0.5	
Adhesive Tape Width	W1	13.00	0.512	±0.5	
Adhesive Tape Position	W2	4.00	0.157	Max	
Tape Width	W3	18.00	0.709	±0.75	



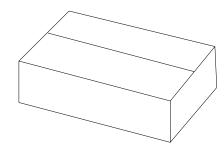
### **Packing Specification**

Inner Carton





Outside Carton



	EVERLIGHT	
CPN:		
P/N:XXX	XXXXXXX	
		RoHS
XXX/XXX	XX-XXXX	
QTY : XX	XXX	CAT:XX
		HUE:XX
LOT NO 3		REF:XX
MA	ADE IN TAIWA	N

- Label Form Specification
   CPN: Customer's Production Number
   P/N : Production Number
   QTY: Packing Quantity
   CAT: Rank of Luminous Intensity
   HUE: Rank of Dominant Wavelength
   REF: Reference
   LOT No: Lot Number
   MADE IN TAIWAN: Production Place
- Packing Quantity
   1. 2000 PCS/1 Inner Carton
  - 2. 10Inner Cartons/1 Outside Carton

Everlight Electronics Co., Ltd. Device Number : DT1-548-037 http\\:www.everlight.com Prepared date: 03-10-2008 Rev 1Page: 7 of 10Prepared by: Grace Shen

# 5484BN/R3DC-AEFC/XR/MS

**EVERLIGHT** 

# **Technical Data Sheet**

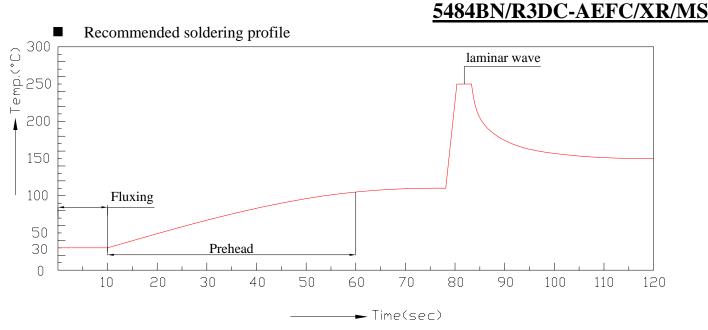
## 5484BN/R3DC-AEFC/XR/MS

#### Notes

- 1. Lead Forming
  - During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.
  - Lead forming should be done before soldering.
  - Avoid stressing the LED package during leads forming. The stress to the base may damage the LED's characteristics or it may break the LEDs.
  - Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause failure of the LEDs.
  - When mounting the LEDs onto a PCB, the PCB holes must be aligned exactly with the lead position of the LED. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.
- 2. Storage
  - The LEDs should be stored at 30°C or less and 70%RH or less after being shipped from Everlight and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
  - Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.
- 3. Soldering
  - Careful attention should be paid during soldering. When soldering, leave more then 3mm from solder joint to epoxy bulb, and soldering beyond the base of the tie bar is recommended.
  - Recommended soldering conditions:

Hand Soldering		DIP Soldering		
Temp. at tip of iron	300℃ Max. (30W Max.)	Preheat temp.	100°C Max. (60 sec Max.)	
Soldering time	3 sec Max.	Bath temp. & time	260 Max., 5 sec Max	
Distance	3mm Min.(From	Distance	3mm Min. (From	
	solder joint to		solder joint to epoxy	
	epoxy bulb)		bulb)	





- Avoiding applying any stress to the lead frame while the LEDs are at high temperature particularly when soldering.
- Dip and hand soldering should not be done more than one time
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- Although the recommended soldering conditions are specified in the above table, dip or handsoldering at the lowest possible temperature is desirable for the LEDs.
- Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.
- 4. Cleaning
  - When necessary, cleaning should occur only with isopropyl alcohol at room temperature for a duration of no more than one minute. Dry at room temperature before use.
  - Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Ultrasonic cleaning shall be pre-qualified to ensure this will not cause damage to the LED.

**EVERLIGHT** 

# **Technical Data Sheet**

### 5484BN/R3DC-AEFC/XR/MS

#### 5. Heat Management

- Heat management of LEDs must be taken into consideration during the design stage of LED application. The current should be de-rated appropriately by referring to the de-rating curve found in each product specification.
- The temperature surrounding the LED in the application should be controlled. Please refer to the data sheet de-rating curve.
- 6. ESD (Electrostatic Discharge)
  - Electrostatic discharge (ESD) or surge current (EOS) can damage LEDs.
  - An ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling LEDs.
  - All devices, equipment and machinery must be properly grounded.
  - Use ion blower to neutralize the static charge which might have built up on surface of the LEDs plastic lens as a result of friction between LEDs during storage and handing.
- 7. Other
  - Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
  - When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
  - These specification sheets include materials protected under copyright of EVERLIGHT corporation. Please don't reproduce or cause anyone to reproduce them without EVERLIGHT's consent.

**EVERLIGHT ELECTRONICS CO., LTD.** Office: No 25, Lane 76, Sec 3, Chung Yang Rd, Tucheng, Taipei 236, Taiwan, R.O.C

*Tel:* 886-2-2267-2000, 2267-9936 *Fax:* 886-2267-6244, 2267-6189, 2267-6306 *http:\\www.everlight.com* 

Everlight Electronics Co., Ltd. Device Number : DT1-548-037 http\\:www.everlight.com Prepared date: 03-10-2008 Rev 1Page: 10 of 10Prepared by: Grace Shen